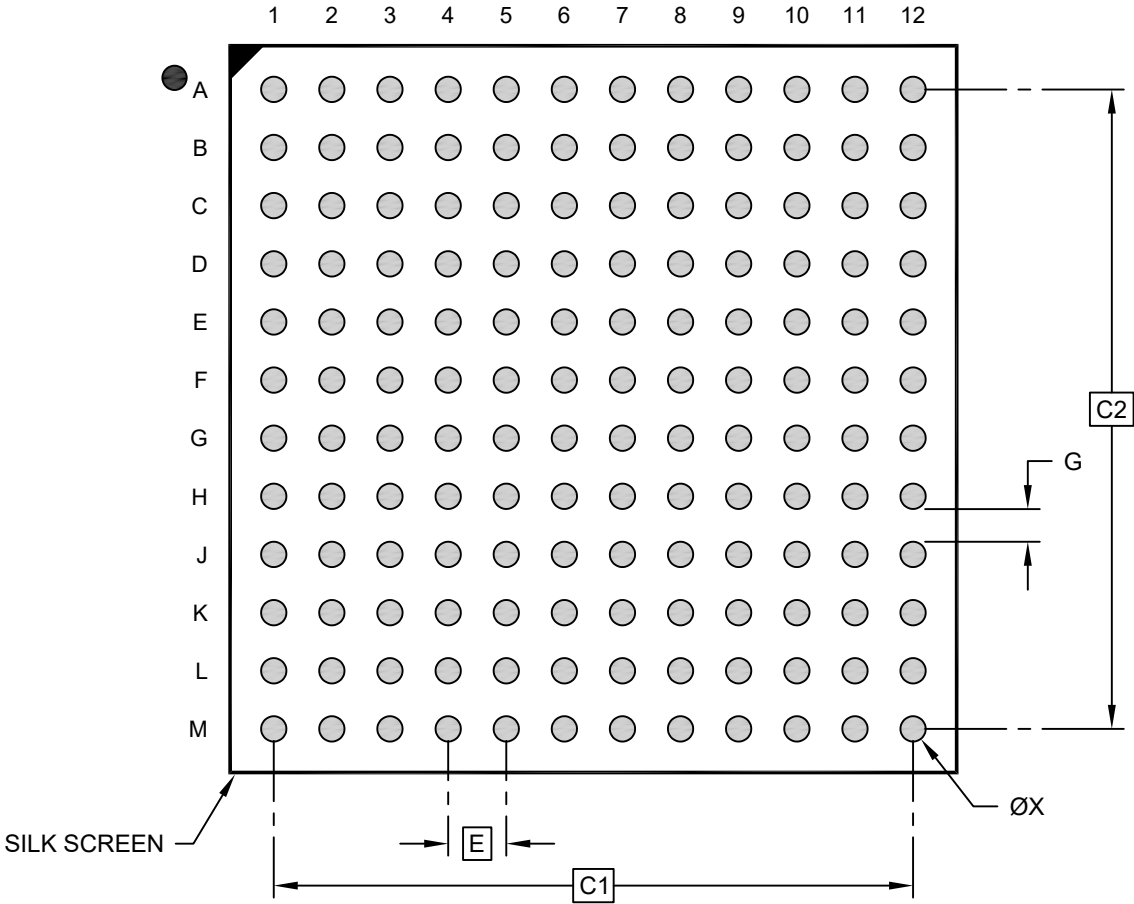


144-Ball Thin Fine-Pitch Ball Grid Array Package (HQB) - 10x10x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.80 BSC		
Contact Pad Spacing	C1		8.80 BSC		
Contact Pad Spacing	C2		8.80 BSC		
Contact Pad Diameter (X144)	X				0.35
Contact Pad to Contact Pad	G		0.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process